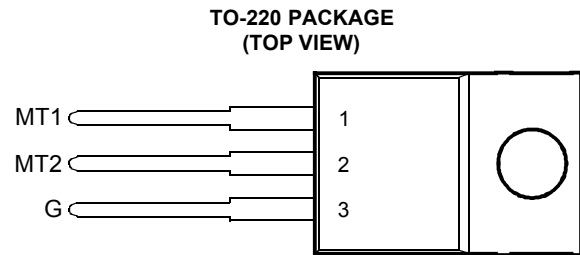


- **High Current Triacs**
- **12 A RMS**
- **Glass Passivated Wafer**
- **400 V to 800 V Off-State Voltage**
- **Max I_{GT} of 50 mA (Quadrants 1 - 3)**



Pin 2 is in electrical contact with the mounting base.

MDC2ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

| RATING | | SYMBOL | VALUE | UNIT |
|---|---------|--------------|-------------|------|
| Repetitive peak off-state voltage (see Note 1) | TIC236D | V_{DRM} | 400 | V |
| | TIC236M | | 600 | |
| | TIC236S | | 700 | |
| | TIC236N | | 800 | |
| Full-cycle RMS on-state current at (or below) 70°C case temperature (see Note 2) | | $I_{T(RMS)}$ | 12 | A |
| Peak on-state surge current full-sine-wave at (or below) 25°C case temperature (see Note 3) | | I_{TSM} | 100 | A |
| Peak gate current | | I_{GM} | ±1 | A |
| Operating case temperature range | | T_C | -40 to +110 | °C |
| Storage temperature range | | T_{stg} | -40 to +125 | °C |
| Lead temperature 1.6 mm from case for 10 seconds | | T_L | 230 | °C |

- NOTES: 1. These values apply bidirectionally for any value of resistance between the gate and Main Terminal 1.
2. This value applies for 50-Hz full-sine-wave operation with resistive load. Above 70°C derate linearly to 110°C case temperature at the rate of 300 mA/°C.
3. This value applies for one 50-Hz full-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.

electrical characteristics at 25°C case temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | | MIN | TYP | MAX | UNIT |
|---|-------------------------------------|----------------------|---------------------------------|-----|------|------|------|
| I_{DRM} Repetitive peak off-state current | $V_D = \text{Rated } V_{DRM}$ | $I_G = 0$ | $T_C = 110^\circ\text{C}$ | | | ±2 | mA |
| I_{GT} Gate trigger current | $V_{supply} = +12\text{ V}^\dagger$ | $R_L = 10\ \Omega$ | $t_{p(g)} > 20\ \mu\text{s}$ | | 12 | 50 | mA |
| | $V_{supply} = +12\text{ V}^\dagger$ | $R_L = 10\ \Omega$ | $t_{p(g)} > 20\ \mu\text{s}$ | | -19 | -50 | |
| | $V_{supply} = -12\text{ V}^\dagger$ | $R_L = 10\ \Omega$ | $t_{p(g)} > 20\ \mu\text{s}$ | | -16 | -50 | |
| | $V_{supply} = -12\text{ V}^\dagger$ | $R_L = 10\ \Omega$ | $t_{p(g)} > 20\ \mu\text{s}$ | | 34 | | |
| V_{GT} Gate trigger voltage | $V_{supply} = +12\text{ V}^\dagger$ | $R_L = 10\ \Omega$ | $t_{p(g)} > 20\ \mu\text{s}$ | | 0.8 | 2 | V |
| | $V_{supply} = +12\text{ V}^\dagger$ | $R_L = 10\ \Omega$ | $t_{p(g)} > 20\ \mu\text{s}$ | | -0.8 | -2 | |
| | $V_{supply} = -12\text{ V}^\dagger$ | $R_L = 10\ \Omega$ | $t_{p(g)} > 20\ \mu\text{s}$ | | -0.8 | -2 | |
| | $V_{supply} = -12\text{ V}^\dagger$ | $R_L = 10\ \Omega$ | $t_{p(g)} > 20\ \mu\text{s}$ | | 0.9 | 2 | |
| V_T On-state voltage | $I_{TM} = \pm 17\text{ A}$ | $I_G = 50\text{ mA}$ | (see Note 4) | | ±1.4 | ±2.1 | V |
| I_H Holding current | $V_{supply} = +12\text{ V}^\dagger$ | $I_G = 0$ | Init' $I_{TM} = 100\text{ mA}$ | | 22 | 40 | mA |
| | $V_{supply} = -12\text{ V}^\dagger$ | $I_G = 0$ | Init' $I_{TM} = -100\text{ mA}$ | | -12 | -40 | |

† All voltages are with respect to Main Terminal 1.

NOTE 4: This parameter must be measured using pulse techniques, $t_p \leq 1\text{ ms}$, duty cycle $\leq 2\%$. Voltage-sensing contacts separate from the current carrying contacts are located within 3.2 mm from the device body.

PRODUCT INFORMATION

Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.

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electrical characteristics at 25°C case temperature (unless otherwise noted) (continued)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|---|-----------|-----------|-----------|------------------|
| I_L Latching current | $V_{supply} = +12\text{ V} \dagger$ $V_{supply} = -12\text{ V} \dagger$ (see Note 5) | | | 80 -80 | mA |
| dv/dt Critical rate of rise of off-state voltage | $V_D = \text{Rated } V_D$ $I_G = 0$ $T_C = 110^\circ\text{C}$ | | ± 400 | | V/ μs |
| $dv/dt_{(c)}$ Critical rise of commutation voltage | $V_D = \text{Rated } V_D$ $di/dt = 0.5 I_{T(RMS)}/\text{ms}$ $T_C = 80^\circ\text{C}$ $I_T = 1.4 I_{T(RMS)}$ | ± 1.2 | ± 9 | | V/ μs |
| di/dt Critical rate of rise of on-state current | $V_D = \text{Rated } V_D$ $di_G/dt = 50\text{ mA}/\mu\text{s}$ $I_{GT} = 50\text{ mA}$ $T_C = 110^\circ\text{C}$ | | ± 100 | | A/ μs |

\dagger All voltages are with respect to Main Terminal 1.

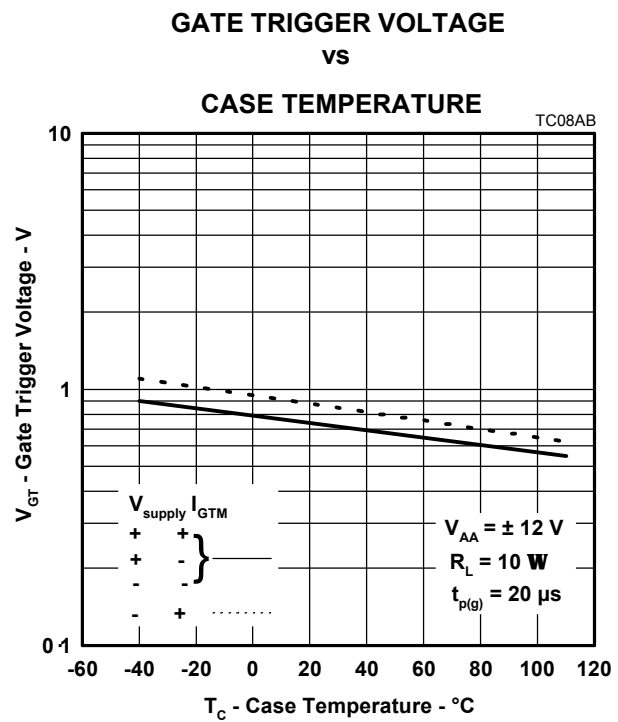
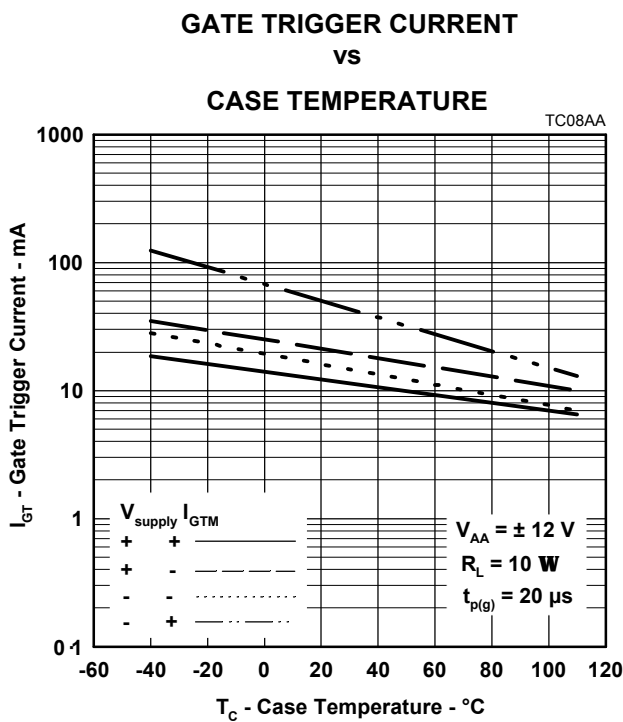
NOTE 5: The triacs are triggered by a 15-V (open-circuit amplitude) pulse supplied by a generator with the following characteristics:

$R_G = 100\ \Omega$, $t_{p(g)} = 20\ \mu\text{s}$, $t_r \leq 15\text{ ns}$, $f = 1\text{ kHz}$.

thermal characteristics

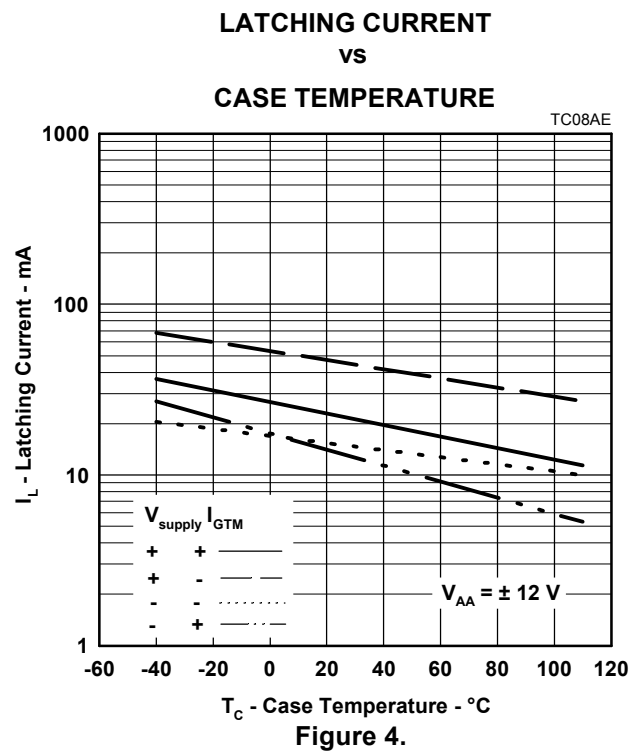
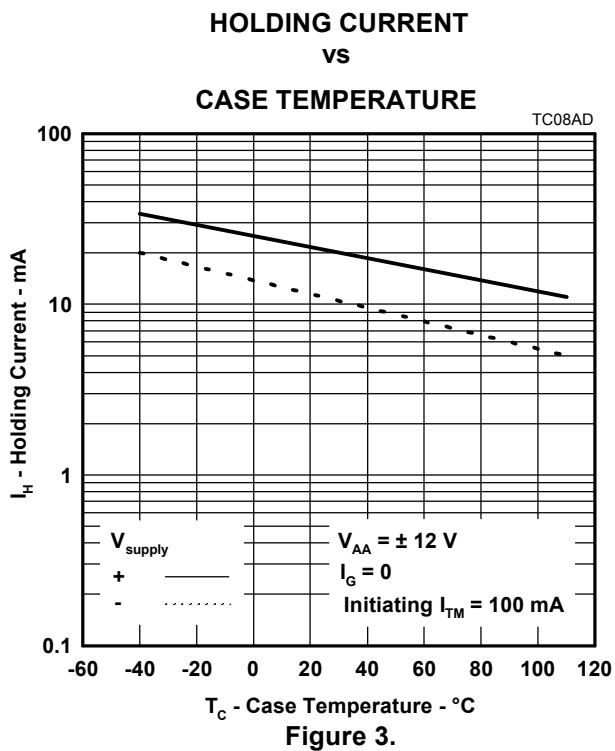
| PARAMETER | MIN | TYP | MAX | UNIT |
|---|-----|-----|------|---------------------------|
| $R_{\theta JC}$ Junction to case thermal resistance | | | 2 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ Junction to free air thermal resistance | | | 62.5 | $^\circ\text{C}/\text{W}$ |

TYPICAL CHARACTERISTICS



PRODUCT INFORMATION

TYPICAL CHARACTERISTICS

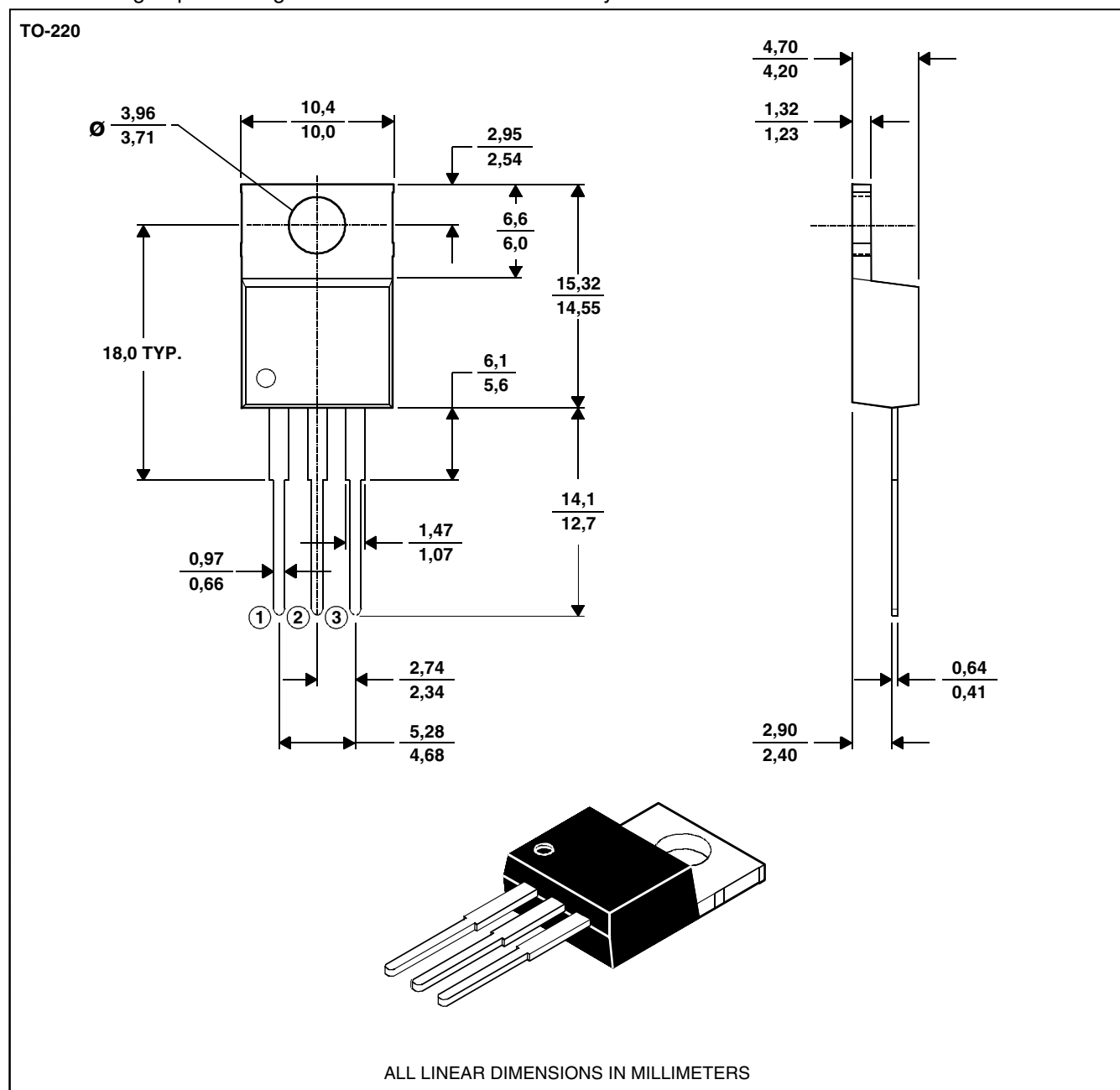


MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

PRODUCT INFORMATION

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